Low-Voltage 1.8/2.5/3.3V 16-Bit D-Type Flip-Flop

With 3.6V-Tolerant Inputs and Outputs (3-State, Non-Inverting)

The NL74VCXH16374 is an advanced performance, non-inverting 16-bit D-type flip-flop. It is designed for very high-speed, very low-power operation in 1.8V, 2.5V or 3.3V systems. The VCX16374 is byte controlled, with each byte functioning identically, but independently. Each byte has separate Output Enable and Clock Pulse inputs. These control pins can be tied together for full 16-bit operation.

When operating at 2.5V (or 1.8V) the part is designed to tolerate voltages it may encounter on either inputs or outputs when interfacing to 3.3V busses. It is guaranteed to be over–voltage tolerant to 3.6V.

The NL74VCXH16374 consists of 16 edge–triggered flip–flops with individual D–type inputs and 3.6V–tolerant 3–state outputs. The clocks (CPn) and Output Enables (\overline{OEn}) are common to all flip–flops within the respective byte. The flip–flops will store the state of individual D inputs that meet the setup and hold time requirements on the LOW–to–HIGH Clock (CP) transition. With the \overline{OE} LOW, the contents of the flip–flops are available at the outputs. When the \overline{OE} is HIGH, the outputs go to the high impedance state. The \overline{OE} input level does not affect the operation of the flip–flops. The data inputs include active bushold circuitry, eliminating the need for external pull–up resistors to hold unused or floating inputs at a valid logic state.

- Designed for Low Voltage Operation: V_{CC} = 1.65–3.6V
- 3.6V Tolerant Inputs and Outputs
- High Speed Operation: 3.0ns max for 3.0 to 3.6V

3.9ns max for 2.3 to 2.7V 7.8ns max for 1.65 to 1.95V

• Static Drive: ±24mA Drive at 3.0V

±18mA Drive at 2.3V ±6mA Drive at 1.65V

- Supports Live Insertion and Withdrawal
- Includes Active Bushold to Hold Unused or Floating Inputs at a Valid Logic State
- IOFF Specification Guarantees High Impedance When $V_{CC} = 0V^{\dagger}$
- Near Zero Static Supply Current in All Three Logic States (20μA)
 Substantially Reduces System Power Requirements
- Latchup Performance Exceeds ±300mA @ 125°C
- ESD Performance: Human Body Model >2000V; Machine Model >200V

†NOTE: To ensure the outputs activate in the 3–state condition, the output enable pins should be connected to V_{CC} through a pull–up resistor. The value of the resistor is determined by the current sinking capability of the output connected to the \overline{OE} pin.



ON Semiconductor

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TSSOP-48 DT SUFFIX CASE 1201

MARKING DIAGRAM

48 **1111 111**

1

A = Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

PIN NAMES

Pins	Function
OEn	Output Enable Inputs
CPn	Clock Pulse Inputs
D0-D15	Inputs
O0-O15	Outputs

ORDERING INFORMATION

Device	Package	Shipping
NL74VCXH16374DT	TSSOP	39 / Rail
NL74VCXH16374DTR	TSSOP	2500 / Reel

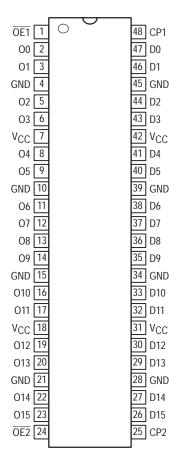


Figure 1. 48-Lead Pinout (Top View)

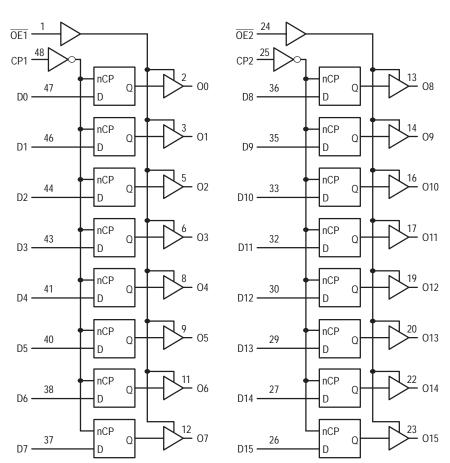
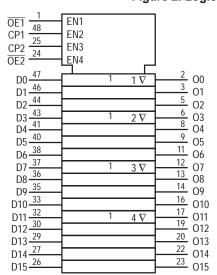


Figure 2. Logic Diagram



	Inputs		Outputs		Inputs		Outputs
CP1	OE1	D0:7	O0:7	CP2	OE2	D8:15	O8:15
1	L	Н	Н	1	L	Н	Н
1	L	L	L	1	L	L	L
Х	L	Х	O0	Х	L	Х	O0
Х	Н	Х	Z	Х	Н	Х	Z

 $H = High Voltage Level; L = Low Voltage Level; Z = High Impedance State; \uparrow = Low-to-High Transition; X = High or Low Voltage Level and Transitions Are Acceptable, for ICC reasons, DO NOT FLOAT Inputs. O0 = No Change.$

ABSOLUTE MAXIMUM RATINGS*

Symbol	Parameter	Value	Condition	Unit
VCC	DC Supply Voltage	-0.5 to +4.6		V
VI	DC Input Voltage	$-0.5 \le V_{\parallel} \le +4.6$		V
VO	DC Output Voltage	$-0.5 \le V_{O} \le +4.6$	Output in 3–State	V
		$-0.5 \le V_{O} \le V_{CC} + 0.5$	Note 1.; Outputs Active	V
lik	DC Input Diode Current	-50	V _I < GND	mA
lok	DC Output Diode Current	-50	V _O < GND	mA
		+50	AO > ACC	mA
IO	DC Output Source/Sink Current	±50		mA
Icc	DC Supply Current Per Supply Pin	±100		mA
I _{GND}	DC Ground Current Per Ground Pin	±100		mA
T _{STG}	Storage Temperature Range	-65 to +150		°C

^{*} Absolute maximum continuous ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute–maximum–rated conditions is not implied.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
Vcc	Supply Voltage	Operating Data Retention Only	1.65 1.2	3.3 3.3	3.6 3.6	٧
VI	Input Voltage		-0.3		3.6	V
Vo	Output Voltage	(Active State) (3–State)	0 0		V _{CC} 3.6	V
ЮН	HIGH Level Output Current, V _{CC} = 3.0V - 3.6V				-24	mA
loL	LOW Level Output Current, V _{CC} = 3.0V – 3.6V				24	mA
ЮН	HIGH Level Output Current, V _{CC} = 2.3V - 2.7V				-18	mA
loL	LOW Level Output Current, V _{CC} = 2.3V – 2.7V				18	mA
ЮН	HIGH Level Output Current, V _{CC} = 1.65 – 1.95V				-6	mA
l _{OL}	LOW Level Output Current, V _{CC} = 1.65 – 1.95V				6	mA
T _A	Operating Free–Air Temperature		-40		+85	°C
Δt/ΔV	Input Transition Rise or Fall Rate, V _{IN} from 0.8V to	2.0V, V _{CC} = 3.0V	0		10	ns/V

^{1.} IO absolute maximum rating must be observed.

DC ELECTRICAL CHARACTERISTICS

			T _A = -40°	C to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V _{IH}	HIGH Level Input Voltage (Note 2.)	1.65V ≤ V _{CC} < 2.3V	0.65 x V _C C		V
		2.3V ≤ V _{CC} ≤ 2.7V	1.6		
		2.7V < V _{CC} ≤ 3.6V	2.0		
VIL	LOW Level Input Voltage (Note 2.)	1.65V ≤ V _{CC} < 2.3V		0.35 x V _{CC}	V
		2.3V ≤ V _{CC} ≤ 2.7V		0.7	
		2.7V < V _{CC} ≤ 3.6V		0.8	
Vон	HIGH Level Output Voltage	1.65V ≤ V _{CC} ≤ 3.6 V; I _{OH} = -100 μA	V _{CC} - 0.2		V
		V _{CC} = 1.65V; I _{OH} = -6mA	1.25		
		V _{CC} = 2.3V; I _{OH} = -6mA	2.0		
		V _{CC} = 2.3V; I _{OH} = -12mA	1.8		
		V _{CC} = 2.3V; I _{OH} = -18mA	1.7		
		V _{CC} = 2.7V; I _{OH} = -12mA	2.2		
		V _{CC} = 3.0V; I _{OH} = -18mA	2.4		
		V _{CC} = 3.0V; I _{OH} = -24mA	2.2		
VOL	LOW Level Output Voltage	$1.65V \le V_{CC} \le 3.6V$; $I_{OL} = 100\mu A$		0.2	V
		V _{CC} = 1.65V; I _{OL} = 6mA		0.3	
		V _{CC} = 2.3V; I _{OL} = 12mA		0.4	
		V _{CC} = 2.3V; I _{OL} = 18mA		0.6	
		V _{CC} = 2.7V; I _{OL} = 12mA		0.4	
		V _{CC} = 3.0V; I _{OL} = 18mA		0.4	
		V _{CC} = 3.0V; I _{OL} = 24mA		0.55	
lı	Input Leakage Current	$1.65V \le V_{CC} \le 3.6V; \ 0V \le V_{I} \le 3.6V$		±5.0	μΑ
I _I (HOLD)	Minimum Bushold Input Current	$V_{CC} = 3.0V, V_{IN} = 0.8V$	75		μΑ
		V _{CC} = 3.0V, V _{IN} = 2.0V	-75		
		V _{CC} = 2.3V, V _{IN} = 0.7V	45		
		V _{CC} = 2.3V, V _{IN} = 1.6V	-45		
		V _{CC} = 1.65V, V _{IN} = 0.57V	25		
		V _{CC} = 1.65V, V _{IN} = 1.07V	-25		
I _I (OD)	Minimum Bushold Over-Drive	V _{CC} = 3.6V, (Note 3.)	450		μΑ
, ,	Current Needed to Change State	V _{CC} = 3.6V, (Note 4.)	-450		
		V _{CC} = 2.7V, (Note 3.)	300		
		V _{CC} = 2.7V, (Note 4.)	-300		
		V _{CC} = 1.95V, (Note 3.)	200		
		V _{CC} = 1.95V, (Note 4.)	-200		
loz	3–State Output Current	$1.65V \le V_{CC} \le 3.6V; \ 0V \le V_O \le 3.6V;$ $V_I = V_{IH} \text{ or } V_{IL}$		±10	μА
lOFF	Power-Off Leakage Current	$V_{CC} = 0V$; V_I or $V_O = 3.6V$		10	μΑ
ICC	Quiescent Supply Current (Note 5.)	1.65V ≤ V _{CC} ≤ 3.6V; V _I = GND or V _{CC}		20	μΑ
		1.65V ≤ V _{CC} ≤ 3.6V; 3.6V ≤ V _I , V _O ≤ 3.6V		±20	μΑ
Δl _{CC}	Increase in I _{CC} per Input	$2.7V < V_{CC} \le 3.6V; V_{IH} = V_{CC} - 0.6V$		750	μА

^{2.} These values of V_I are used to test DC electrical characteristics only.

3. An external driver must source at least the specified current to switch from LOW–to–HIGH

4. An external driver must source at least the specified current to switch from HIGH–to–LOW

5. Outputs disabled or 3–state only.

AC CHARACTERISTICS (Note 6.; $t_R = t_F = 2.0 \text{ns}$; $C_L = 30 \text{pF}$; $R_L = 500 \Omega$)

			Limits						
				T _A = -40°C to +85°C					
			V _{CC} = 3.0	OV to 3.6V	V _{CC} = 2.3	3V to 2.7V	V _{CC} = 1.6	5 to 1.95V	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
f _{max}	Clock Pulse Frequency	1	250		200		100		MHz
tPLH tPHL	Propagation Delay CP to On	1	0.8 0.8	3.0 3.0	1.0 1.0	3.9 3.9	1.5 1.5	7.8 7.8	ns
^t PZH ^t PZL	Output Enable Time to High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	4.6 4.6	1.5 1.5	9.2 9.2	ns
^t PHZ ^t PLZ	Output Disable Time From High and Low Level	2	0.8 0.8	3.5 3.5	1.0 1.0	3.8 3.8	1.5 1.5	6.8 6.8	ns
t _S	Setup Time, High or Low Dn to CP	3	1.5		1.5		2.5		ns
t _h	Hold Time, High or Low Dn to CP	3	1.0		1.0		1.0		ns
t _W	CP Pulse Width, High	3	1.5		1.5		4.0		ns
^t OSHL ^t OSLH	Output-to-Output Skew (Note 7.)			0.5 0.5		0.5 0.5		0.75 0.75	ns

^{6.} For C_L = 50pF, add approximately 300ps to the AC maximum specification.

DYNAMIC SWITCHING CHARACTERISTICS

			T _A = +25°C	
Symbol	Characteristic	Condition	Тур	Unit
VOLP	Dynamic LOW Peak Voltage	$V_{CC} = 1.8V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	0.25	V
	(Note 8.)	$V_{CC} = 2.5V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	0.6]
		$V_{CC} = 3.3V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	0.8	
VOLV	Dynamic LOW Valley Voltage	$V_{CC} = 1.8V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	-0.25	V
	(Note 8.)	$V_{CC} = 2.5V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	-0.6]
		$V_{CC} = 3.3V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	-0.8	
VOHV	Dynamic HIGH Valley Voltage	$V_{CC} = 1.8V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	1.5	V
	(Note 9.)	$V_{CC} = 2.5V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	1.9]
		$V_{CC} = 3.3V$, $C_L = 30pF$, $V_{IH} = V_{CC}$, $V_{IL} = 0V$	2.2	

^{8.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Unit
C _{IN}	Input Capacitance	Note 10.	6	pF
COUT	Output Capacitance	Note 10.	7	pF
C _{PD}	Power Dissipation Capacitance	Note 10., 10MHz	20	pF

10. V_{CC} = 1.8, 2.5 or 3.3V; V_I = 0V or V_{CC} .

Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device.
 The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toshL) or LOW-to-HIGH (toslH); parameter guaranteed by design.

^{9.} Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the HIGH state.

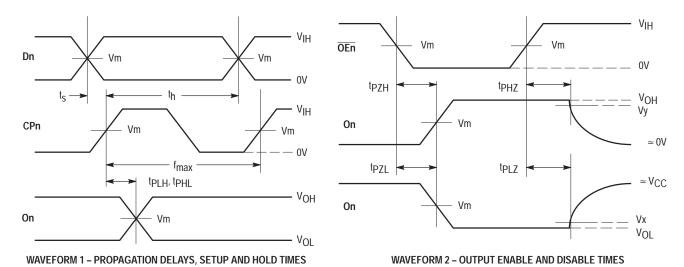
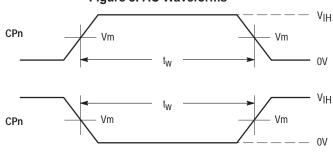


Figure 3. AC Waveforms

 t_R = t_F = 2.0ns, 10% to 90%; f = 1MHz; t_W = 500ns

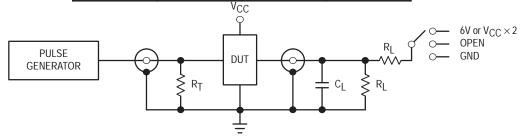
 $t_R = t_F = 2.0$ ns, 10% to 90%; f = 1MHz; $t_W = 500$ ns



WAVEFORM 3 - PULSE WIDTH $t_R = t_F = 2.0$ ns (or fast as required) from 10% to 90%

Figure 4. AC Waveforms

	VCC			
Symbol	3.3V ±0.3V	2.5V ±0.2V	1.8V ±0.15V	
V _{IH}	2.7V	Vcc	Vcc	
V _m	1.5V	V _{CC} /2	V _{CC} /2	
V _X	V _{OL} + 0.3V	V _{OL} + 0.15V	V _{OL} + 0.15V	
Vy	V _{OH} – 0.3V	V _{OH} – 0.15V	V _{OH} – 0.15V	



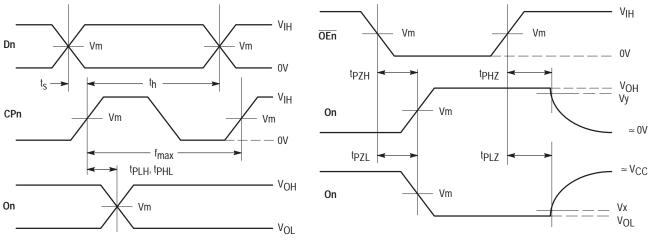
TEST	SWITCH
tPLH, tPHL	Open
tPZL, tPLZ	6V at $V_{CC} = 3.3 \pm 0.3V$; $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$; $1.8V \pm 0.15V$
tPZH, tPHZ	GND

C_L = 30pF or equivalent (Includes jig and probe capacitance)

 $R_{L} = 500\Omega$ or equivalent

 $R_T = Z_{OUT}$ of pulse generator (typically 50 Ω)

Figure 5. Test Circuit

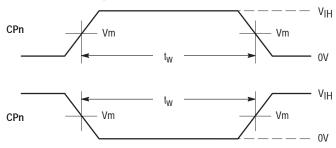


WAVEFORM 4 - PROPAGATION DELAYS, SETUP AND HOLD TIMES

 $t_R = t_F = 2.0$ ns, 10% to 90%; f = 1MHz; $t_W = 500$ ns

WAVEFORM 5 – OUTPUT ENABLE AND DISABLE TIMES $t_R = t_F = 2.0$ ns, 10% to 90%; f = 1MHz; $t_W = 50$ 0ns

Figure 6. AC Waveforms



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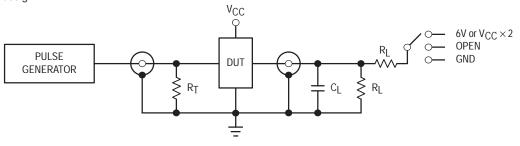
Figure 7. AC Waveforms

	Vcc		
Symbol	3.3V ±0.3V	2.7V	
VIH	2.7V	2.7V	
V _m	1.5V	1.5V	
V _X	V _{OL} + 0.3V	V _{OL} + 0.3V	
Vy	V _{OH} – 0.3V	V _{OH} – 0.3V	

AC CHARACTERISTICS ($t_R = t_F = 2.0$ ns; $C_L = 50$ pF; $R_L = 500\Omega$)

			Limits				
			T _A = -40°C to +85°C				1
			V _{CC} = 3.0V to 3.6V V _{CC} = 2.7V		= 2.7V	1	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Unit
f _{max}	Clock Pulse Frequency	4	150		150		MHz
^t PLH ^t PHL	Propagation Delay CP to On	4	1.0 1.0	4.2 4.2		4.9 4.9	ns
^t PZH ^t PZL	Output Enable Time to High and Low Level	5	1.0 1.0	4.8 4.8		5.9 5.9	ns
^t PHZ ^t PLZ	Output Disable Time From High and Low Level	5	1.0 1.0	4.3 4.3		4.7 4.7	ns
^t OSHL ^t OSLH	Output-to-Output Skew (Note 11.)			0.5 0.5		0.5 0.5	ns

^{11.} Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toshL) or LOW-to-HIGH (toshH); parameter guaranteed by design.



TEST	SWITCH
tPLH, tPHL	Open
tPZL, tPLZ	6V at $V_{CC} = 3.3 \pm 0.3V$; $V_{CC} \times 2$ at $V_{CC} = 2.5 \pm 0.2V$; 1.8V $\pm 0.15V$
tpzh, tphz	GND

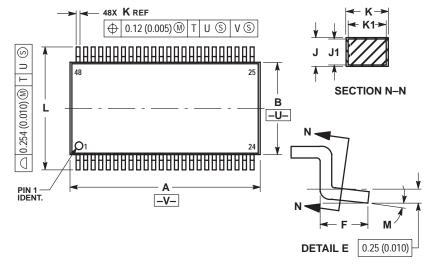
 $C_L = 50 pF$ or equivalent (Includes jig and probe capacitance)

 $R_L = 500\Omega$ or equivalent $R_T = Z_{OUT}$ of pulse generator (typically 50Ω)

Figure 8. Test Circuit

PACKAGE DIMENSIONS

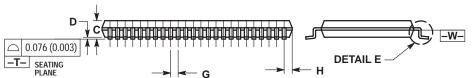
TSSOP DT SUFFIX CASE 1201-01 ISSUE A

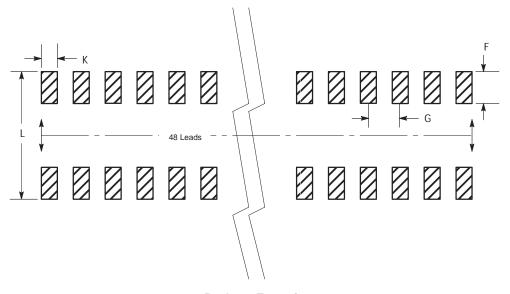


- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS. SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION K DOES NOT INCLUDE DAMBAR
 - PROTRUSION. ALLOWABLE DAMBAR
 PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.
- TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
 DIMENSIONS A AND B ARE TO BE
 DETERMINED AT DATUM PLANE -W-.

	MILLIN	METERS	INCHES			
DIM	MIN	MAX	MIN	MAX		
Α	12.40	12.60	0.488	0.496		
В	6.00	6.20	0.236	0.244		
С		1.10		0.043		
D	0.05	0.15	0.002	0.006		
F	0.50	0.75	0.020	0.030		
G	0.50	BSC	0.0197 BSC			
Н	0.37		0.015			
J	0.09	0.20	0.004	0.008		
J1	0.09	0.16	0.004	0.006		
K	0.17	0.27	0.007	0.011		
K1	0.17	0.23	0.007	0.009		
L	7.95	8.25	0.313	0.325		
M	0 °	8 °	0 °	8 °		





Package Footprint

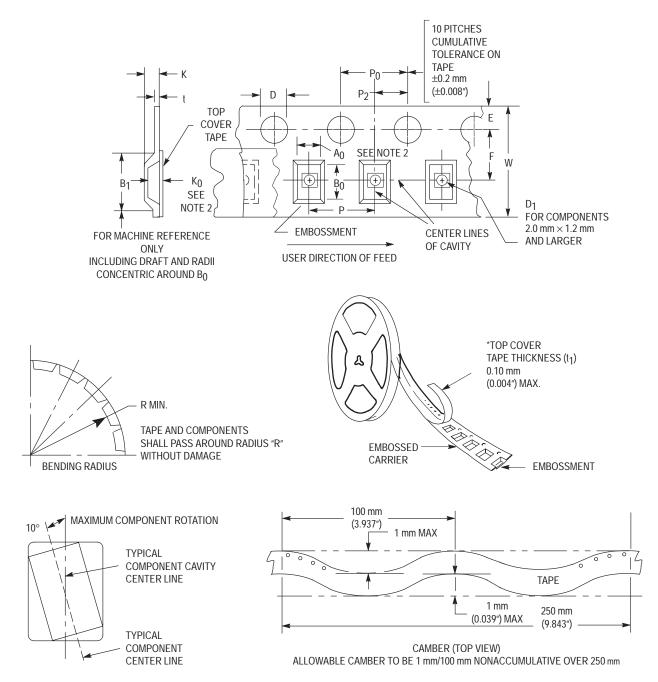


Figure 9. Carrier Tape Specifications

EMBOSSED CARRIER DIMENSIONS (See Notes 1 and 2)

Tape Size	B ₁ Max	D	D ₁	E	F	К	Р	P ₀	P ₂	R	Т	w
24mm	20.1mm (0.791")	1.5 + 0.1mm -0.0 (0.059 +0.004" -0.0)	1.5mm Min (0.060")	1.75 ±0.1 mm (0.069 ±0.004")	11.5 ±0.10 mm (0.453 ±0.004")	11.9 mm Max (0.468")	16.0 ±0.1 mm (0.63 ±0.004")	4.0 ±0.1 mm (0.157 ±0.004")	2.0 ±0.1 mm (0.079 ±0.004")	30 mm (1.18")	0.6 mm (0.024")	24.3 mm (0.957")

- 1. Metric Dimensions Govern-English are in parentheses for reference only.
- 2. A₀, B₀, and K₀ are determined by component size. The clearance between the components and the cavity must be within 0.05 mm min to 0.50 mm max. The component cannot rotate more than 10° within the determined cavity

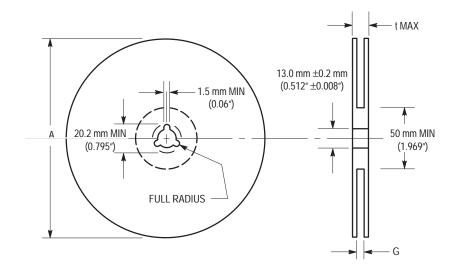


Figure 10. Reel Dimensions

REEL DIMENSIONS

Tape Size	A Max	G	t Max	
24 mm	360 mm	24.4 mm + 2.0 mm, -0.0	30.4 mm	
	(14.173")	(0.961" + 0.078", -0.00)	(1.197")	

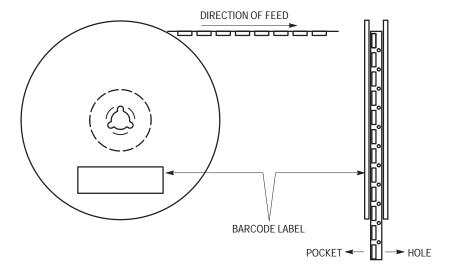


Figure 11. Reel Winding Direction

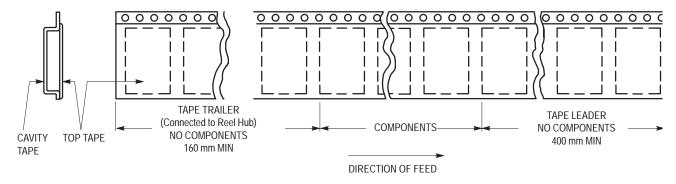


Figure 12. Tape Ends for Finished Goods

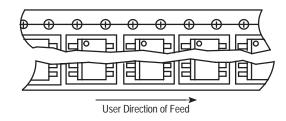


Figure 13. Reel Configuration

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